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(54) **SYSTEM AND METHOD FOR
HIGH-TEMPERATURE LAMINATION OF
PRINTED CIRCUIT BOARDS**

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ABSTRACT

A press pad for use in lamination of multi-layer circuit boards is disclosed. The press pad includes: a planar pad having a first surface and a second surface opposite to the first surface; and a sheet of release film coupled to the first surface, wherein the release film sheet is coupled to the first surface using an acrylic-based adhesive containing thermoplastic polyolefin and methyl acrylate, and wherein the release film sheet comprises polyimide-based film.

